

What is claimed is:

- (1) A laminate for HDD suspension comprises a stainless steel layer, a polyimide resin layer and a conductor layer wherein said conductor layer is a copper foil or a copper alloy foil having a thickness of 14  $\mu\text{m}$  or less, a tensile strength of 400 MPa or more and a conductance of 65% or more.
- (2) A laminate for HDD suspension as described in claim 1 wherein the thickness of the stainless steel layer is in the range of 12-30  $\mu\text{m}$ .
- (3) A laminate for HDD suspension as described in claim 1 wherein the thickness of the polyimide resin layer is in the range of 5-20  $\mu\text{m}$ .
- (4) A laminate for HDD suspension as described in claim 1 wherein the conductor layer is a rolled copper alloy foil having a tensile strength of 500 MPa or more and a conductance of 65% or more.
- (5) A laminate for HDD suspension as described in claim 1 wherein said laminate is constituted of a stainless steel layer, a polyimide resin layer and a conductor layer, the conductor layer is a copper foil or a copper alloy foil having a thickness of 7-14  $\mu\text{m}$ , a tensile strength of 500 MPa or more and a conductance of 65% or more, the stainless steel layer has a thickness in the range of 12-30  $\mu\text{m}$ , the polyimide resin layer has a thickness in the range of 5-20  $\mu\text{m}$  and the total thickness is in the range of 20-50  $\mu\text{m}$ .
- (6) A method for manufacturing a laminate for HDD suspension which comprises applying a solution of a polyimide resin or a precursor thereof to a stainless steel layer, giving a heat treatment to form a polyimide resin layer, placing a rolled copper alloy foil having a thickness of 14  $\mu\text{m}$  or less, a tensile strength of 500 MPa or more and a conductance of 65% or more on the aforementioned polyimide resin layer and hot pressing at 1-20 MPa and 280°C or above to give a laminate constituted of a stainless steel layer, a

polyimide resin layer and a conductor layer.